

# **EZV873**

Product Change Notification - JAON-10VI
Date:

21 Nov 2019

**Product Category:** 

Switchtec

Affected CPNs:



### **Notification subject:**

CCB 3778 Final Notice: Qualification of STAK as an additional bumping facility and assembly site for selected Microsemi PM85xx device families available in 1311L BBGA (37.5x37.5x3.40mm) package.

**Notification text:** 

#### **PCN Status:**

Final notification.

## **PCN Type:**

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of STAK as an additional bumping facility and assembly site for selected Microsemi PM85xx device families available in 1311L BBGA (37.5x37.5x3.40mm) package.

### Pre Change:

Assembled at ATK site and bumping facility at ATT using NAU-27-1F underfill material.

## **Post Change:**

Assembled at ATK site and bumping facility at ATT using NAU-27-1F underfill material or assembled and bumping facility at STAK site using UF8830S underfill material.

Pre and Post Change Summary:

	Pre Change	Post C	hange		
Assembly Site	Amkor Technology Korea (K4), INC. (ATK)	Amkor Technology Korea (K4), INC. (ATK)	Stats Chippac Korea Ltd. (STAK)		
Bumping facility	Amkor Technology Taiwan (ATT)	Amkor Technology Taiwan (ATT)			
Bump material	SnAg	SnAg	SnAg		
Underfill material	NAU-27-1F	NAU-27-1F	UF8830S		

#### Impacts to Data Sheet:



None

## **Change Impact:**

None

### **Reason for Change:**

To improve on time delivery performance by qualifying STAK as an additional bumping facility and assembly site.

#### **Change Implementation Status:**

In Progress

### **Estimated First Ship Date:**

December 21, 2019 (date code: 1951)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

## **Time Table Summary:**

	May 2019				>	November 2019				December 2019					
Workweek	18	19	20	21	22	1	44	45	46	47	48	49	50	51	52
Initial PCN Issue Date	X														
Qual Report										_					
Availability										^					
Final PCN Issue Date										Χ					
Estimated														Υ	
Implementation Date														^	

### Method to Identify Change:

Traceability code

#### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

#### **Revision History:**

May 3, 2019: Issued initial notification.

**November 21, 2019:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 21, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_JAON-10VFZV873\_REPORT.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.



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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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### Affected Catalog Part Numbers (CPN)

PM8534B-FEI

PM8535B-FEI

PM8536B-FEI

PM8544B-FEI

PM8545B-FEI

PM8546B-FEI

PM8554B-FEI

PM8555B-FEI

PM8556B-FEI

PM8564B-FEI

PM8565B-FEI

PM8566B-FEI

PM8574B-FEI

PM8575B-FEI

PM8576B-FEI

Date: Thursday, November 21, 2019